

**Polymer
 PTC Devices**

Surface mount fuses

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LP-NSM012

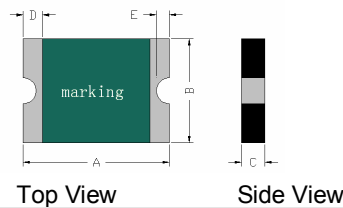
Features

- Small size of 1206
- Lead-free and compliant with the European Union RoHS Directive 2011/65/EU
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA、TUV



Product Dimensions (mm)

Part number	A Max.	B Max.	C Max.	D Min.	E Min.	Part marking
LP-NSM012	3.50	1.80	0.85	0.25	0.10	P



Electrical Characteristics

Part number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} Current(A) Time(S)	P _{d typ} (W)	R _{min} (Ω)	R _{1max} (Ω)
LP-NSM012	0.125	0.29	30	20	1.0 0.20	0.6	1.50	6.00

I_H=Hold current: maximum current at which the device will not trip at 25°C still air.

I_T=Trip current: minimum current at which the device will always trip at 25°C still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

I_{max}=Maximum fault current device can withstand without damage at rated voltage.

T_{trip}=Maximum time to trip(s) at assigned current.

P_{d typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

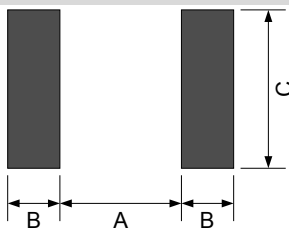
R_{min}=Minimum device resistance at 25°C prior to tripping.

R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Thermal Derating

LP-NSM012	Maximum ambient operating temperature(°C)									
	-40	-20	0	20	25	40	50	60	70	85
Hold Current (A)	0.19	0.16	0.14	0.13	0.125	0.10	0.09	0.08	0.07	0.04

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-NSM012	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase, hot air oven.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

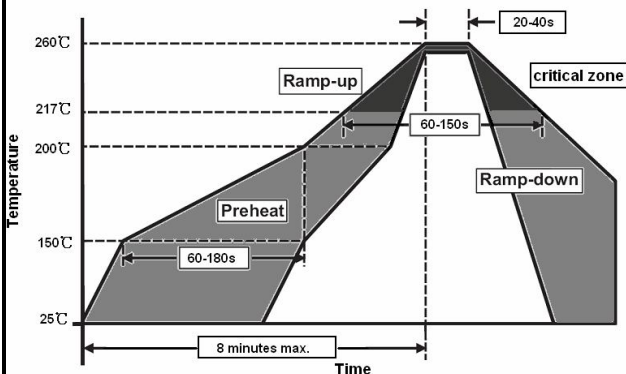
Package Information

Tape & Reel: 4000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

Specifications are subject to change without notice



Average Ramp-Up Rate: 3°C/second max. Ramp-Down Rate: 6°C/second max.

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